

3.2 Block diagram

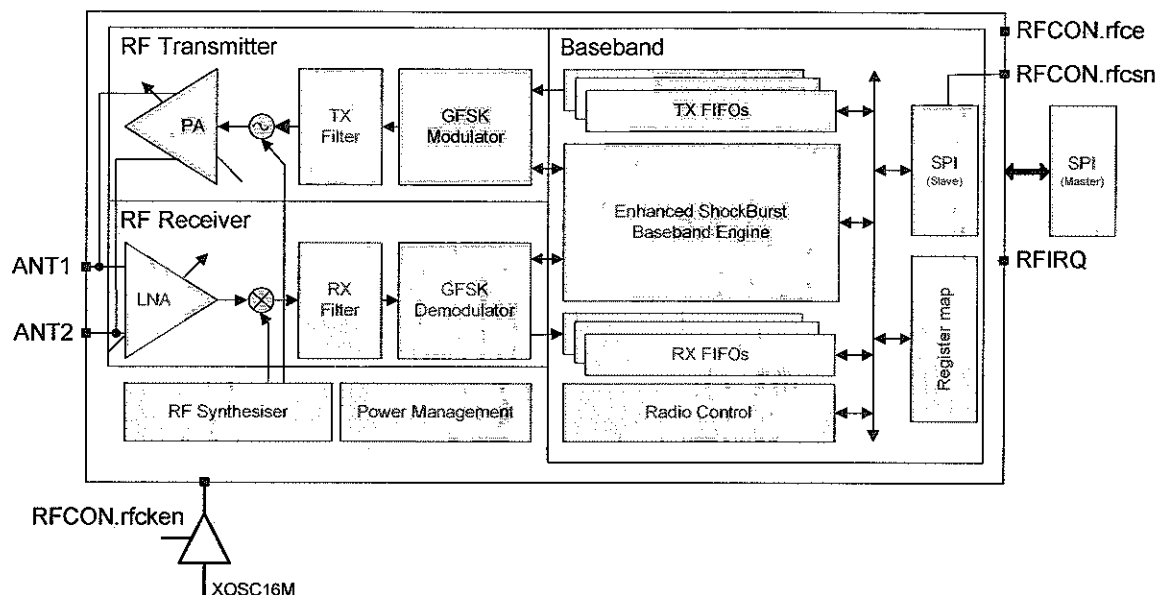


Figure 5. RF transceiver block diagram

3.3 Functional description

This section describes the different operating modes of the RF transceiver and the parameters used to control it.

The RF transceiver module has a built-in state machine that controls the transitions between the different operating modes. The state machine is controlled by SFR register `RFCON` and RF transceiver register `CONFIG`, see [section 3.5](#) for details.

3.3.1 Operational Modes

You can configure the RF transceiver to power down, standby, RX and TX mode. This section describes these modes in detail.

3.3.1.1 State diagram

The state diagram ([Figure 6](#).) shows the operating modes of the RF transceiver and how they function. At the end of the reset sequence the RF transceiver enters Power Down mode. When the RF transceiver enters Power Down mode the MCU can still control the module through the SPI and the `rfcsn` bit in the `RFCON` register.

There are three types of distinct states highlighted in the state diagram:

- **Recommended operating mode:** is a recommended state used during normal operation.
- **Possible operating mode:** is a possible operating state, but is not used during normal operation.
- **Transition state:** is a time limited state used during start up of the oscillator and settling of the PLL.

13 On-chip oscillators

The nRF24LE1 contains two high frequency oscillators and two low frequency oscillators. The primary high frequency clock source is a 16 MHz crystal oscillator. There is also a fast starting 16 MHz RC oscillator, which is used primarily to provide the system with a high frequency clock while it is waiting for the crystal oscillator to start up. The low frequency clock can be supplied by either a 32.768 kHz crystal oscillator or a 32.768 kHz RC oscillator. External 16 MHz and 32.768 kHz clocks may also be used instead of the on-chip oscillators. See section [11.3.1 on page 110](#) for control of the clock sources.

13.1 Features

- Low-power amplitude regulated 16 MHz crystal oscillator
- Fast starting 16 MHz RC oscillator with $\pm 5\%$ frequency accuracy
- Ultra low-power amplitude regulated 32.768 kHz crystal oscillator
- Ultra low-power 32.768 kHz RC oscillator with $\pm 10\%$ frequency accuracy

13.2 Block diagrams

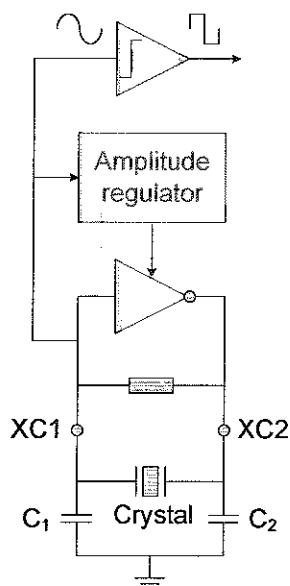


Figure 54. Block diagram of 16 MHz crystal oscillator

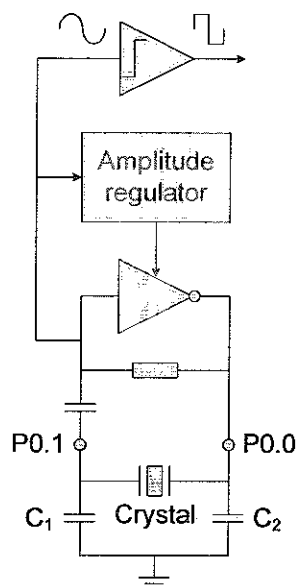


Figure 55. Block diagram of 32.768 kHz crystal oscillator

13.3 Functional description

13.3.1 16 MHz crystal oscillator

The 16 MHz crystal oscillator (XOSC16M) is designed to be used with an AT-cut quartz crystal in parallel resonant mode. To achieve correct oscillation frequency it is very important that the load capacitance matches the specification in the crystal datasheet. The load capacitance is the total capacitance seen by the crystal across its terminals:

$$C_{LOAD} = \frac{C'_1 \cdot C'_2}{C'_1 + C'_2}$$

$$C'_1 = C_1 + C_{PCB1} + C_{PIN}$$

$$C'_2 = C_2 + C_{PCB2} + C_{PIN}$$

C1 and C2 are ceramic SMD capacitors connected between each crystal terminal and VSS, CPCB1 and CPCB2 are stray capacitances on the PCB, while CPIN is the input capacitance on the xc1 and xc2 pins of the nRF24LE1 (typically 1pF). C1 and C2 should be of the same value, or as close as possible.

To ensure a functional radio link the frequency accuracy must be ± 60 ppm or better. The initial tolerance of the crystal, drift over temperature, aging and frequency pulling due to incorrect load capacitance must all be taken into account. For reliable operation the crystal load capacitance, shunt capacitance, equivalent series resistance (ESR) and drive level must comply with the specifications in [Table 114, on page 182](#). It is recommended to use a crystal with lower than maximum ESR if the load capacitance and/or shunt capacitance is high. This will give faster start-up and lower current consumption.

The start-up time is typically about 1 ms for a crystal with 9 pF load capacitance and an ESR specification

of 60 Ω max. This value is valid for crystals in a 3.2×2.5 mm can. If you use the smallest crystal cans (like 2.0×2.5 mm), pay particular attention to the startup time of the crystal. These crystals have a longer startup than crystals in larger cans. To make sure the startup time is <1.5 ms use a crystal for load capacitance of 6 pF. A low load capacitance will reduce both startup time and current consumption. For more details regarding how to measure the startup of a specific crystal, please see the nAN24-13 application note.

The crystal oscillator is normally running only when the system is in active or standby mode. It is possible to keep it on in register retention mode as well, by writing a '1' to bit 7 in the CLKCTRL register (see [Table 57, on page 105](#)). This is recommended if the system is expected to wake up again in less than 5 ms. The reason is that the additional current drawn during start-up makes it more power-efficient to let the oscillator run for a few extra milliseconds than to restart it.

13.3.2 16 MHz RC oscillator

The 16 MHz RC oscillator (RCOSC16M) is used primarily to provide a high speed clock while the crystal oscillator is starting up. It starts in just a few microseconds, and has a frequency accuracy of $\pm 5\%$.

By default, the 16 MHz RC and crystal oscillators are started simultaneously. The RC oscillator supplies the clock until the crystal oscillator has stabilized. The system then makes an automatic switch to the crystal oscillator clock, and turns off the RC oscillator to save power. Bit 3 in the CLKCTRL register can be polled to check which oscillator is currently supplying the high speed clock.

The system can be configured to start only one of the two 16 MHz oscillators. Write bit 4 and 5 in the CLKCTRL register to choose the desired behavior. Note that the RF Transceiver cannot be used while the high frequency clock is sourced by the RC oscillator. The ADC may also have reduced performance.

13.3.3 External 16 MHz clock

The nRF24LE1 may be used with an external 16 MHz clock applied to the xc1 pin. Write a '1' to bit 6 in the CLKCTRL register if the external clock is a rail-to-rail digital signal (This is for test and application development involving no radio link, only. Bit 6 must be cleared in normal operation.) The input signal may also be analog, coming from e.g. the crystal oscillator of a microcontroller. In this case the crystal oscillator on the nRF24LE1 must also be enabled, since it is used to convert the analog input into a digital clock signal. CLKCTRL[6] must be '0', and CLKCTRL[5:4] must be '10' to enable the oscillator. An input amplitude of 0.8V peak-to-peak or higher is recommended to achieve low current consumption and a good signal-to-noise ratio. The DC level is not important as long as the applied signal never rises above VDD or drops below VSS. The xc1 pin will load the microcontrollers crystal with approximately 1 pF in addition to PCB routing. xc2 shall not be connected.

Note: A frequency accuracy of ± 60 ppm or better is required to get a functional radio link.

13.3.4 32.768 kHz crystal oscillator

The 32.768 kHz crystal oscillator (XOSC32K) is operational in all system modes except deep sleep and memory retention, timer off. It is enabled by writing '000' to CLKLFCTRL[2:0].

A crystal must be connected between port pins P0.0 and P0.1, which are automatically configured as crystal pins when the oscillator is enabled. To achieve correct oscillation frequency it is important that the load capacitance matches the specification in the crystal datasheet. The load capacitance is the total capacitance seen by the crystal across its terminals:

$$C_{LOAD} = \frac{C'_1 \cdot C'_2}{C'_1 + C'_2}$$

$$C'_1 = C_1 + C_{PCB1} + C_{PIN}$$

$$C'_2 = C_2 + C_{PCB2} + C_{PIN}$$

C_1 and C_2 are ceramic SMD capacitors connected between each crystal terminal and VSS, C_{PCB1} and C_{PCB2} are stray capacitances on the PCB, while C_{PIN} is the input capacitance on the P0.0 and P0.1 pins of the nRF24LE1 (typically 3pF when configured as crystal pins). C_1 and C_2 should be of the same value, or as close as possible. The oscillator uses an amplitude regulated design similar to the 16 MHz crystal oscillator. For reliable operation the crystal load capacitance, shunt capacitance, equivalent series resistance (ESR) and drive level must comply with the specifications in [Table 114, on page 182](#). It is recommended to use a crystal with lower than maximum ESR if the load capacitance and/or shunt capacitance is high. This will give faster start-up and lower current consumption.

The start-up time is typically less than 0.5s for a crystal with 9pF load capacitance, 1pF shunt capacitance and an ESR of 50kΩ. Bit 6 in the CLKLFCTRL register can be polled to check if the oscillator is ready for use.

13.3.5 32.768 kHz RC oscillator

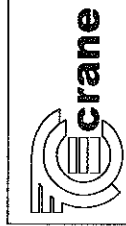
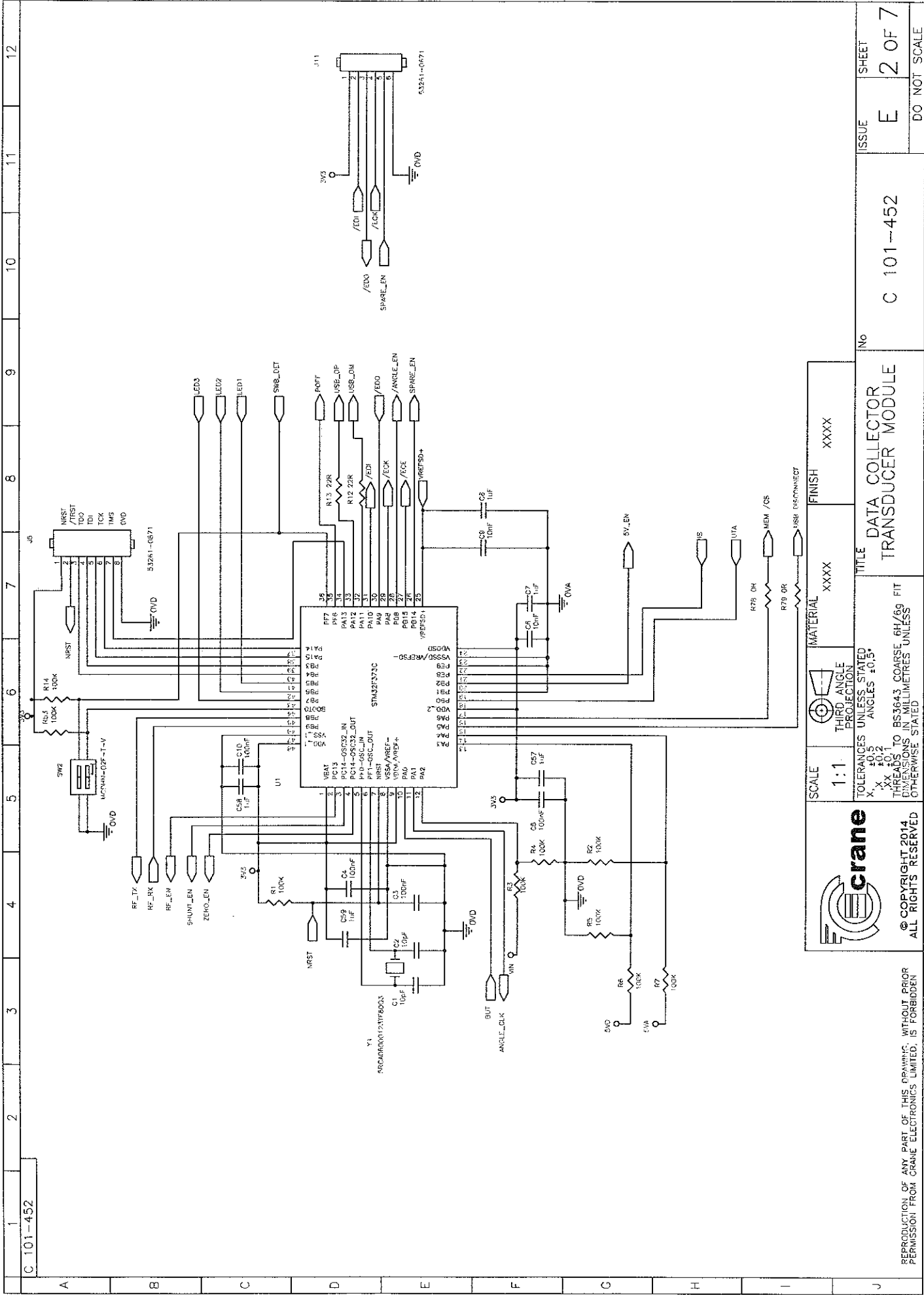
The low frequency clock may be generated by a 32.768 kHz RC oscillator (RCOSC32K) instead of the crystal oscillator, if a frequency accuracy of $\pm 10\%$ is sufficient. This saves the cost of a crystal, and also frees up P0.0 and P0.1 for other applications. The 32.768 kHz RC oscillator is enabled by writing '001' to CLKLFCTRL[2:0]. It typically starts in less than 0.5ms. Bit 6 in the CLKLFCTRL register can be polled to check if the oscillator is ready for use.

13.3.6 Synthesized 32.768 kHz clock

The low frequency clock can also be synthesized from the 16 MHz crystal oscillator clock. Write '010' to CLKLFCTRL[2:0] to select this option. The synthesized clock will only be available in system modes where the 16 MHz crystal oscillator is active. (This will be possible in the operational modes "Register retention," "Standby," and "Active.")

13.3.7 External 32.768 kHz clock

The nRF24LE1 may be used with an external 32.768 kHz clock applied to the P0.1 port pin. Write '100' to CLKLFCTRL[2:0] if the external clock is a rail-to-rail digital signal, or '011' if it is an analog signal coming from e.g. the crystal oscillator of a microcontroller. An analog input signal must have an amplitude of 0.2V peak-to-peak or higher. The DC level is not important as long as the applied signal never rises above VDD or drops below VSS. The P0.1 port pin will load the microcontrollers crystal with approximately 3pF in addition to PCB routing.

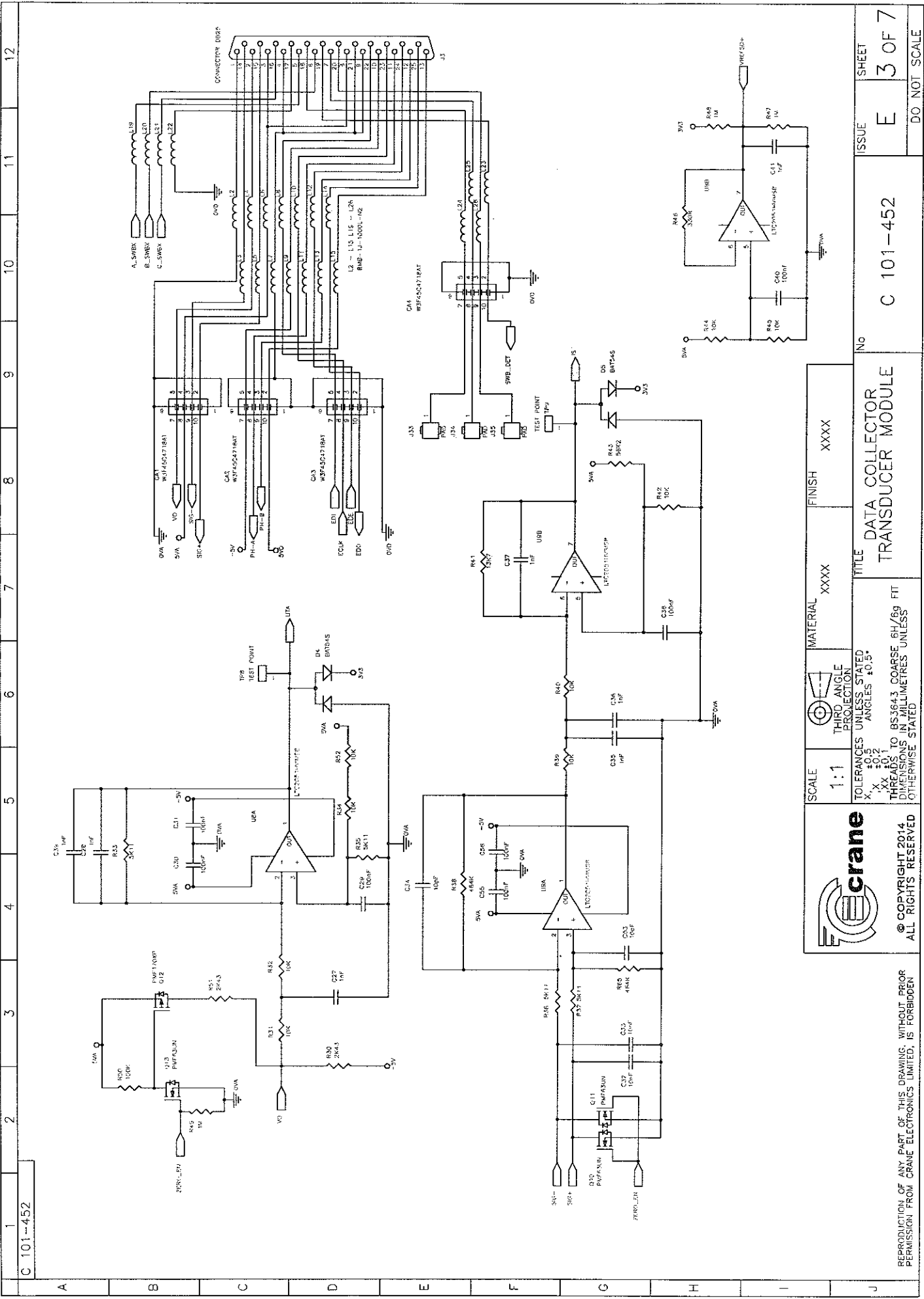


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SCALE 1:1
THIRD ANGLE PROJECTION
TOLERANCES UNLESS STATED
X: ±0.5
Y: ±0.2
Z: ±0.1
DIMENSIONS IN MILLIMETRES UNLESS OTHERWISE STATED

MATERIAL XXXX
FINISH XXXX
TITLE DATA COLLECTOR TRANSDUCER MODULE
No C 101-452

ISSUE E
SHEET 2 OF 7
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SCALE	THIRD ANGLE PROJECTION	MATERIAL	FINISH	TITLE
1:1		XXXX	XXXX	DATA COLLECTOR TRANSDUCER MODULE
TOLERANCES UNLESS STATED X, Y, Z ±0.5 ANGLES ±0.5° THREADS TO BS3643 COARSE 6H/6g FIT DIMENSIONS IN MILLIMETRES UNLESS OTHERWISE STATED				

C 101-452

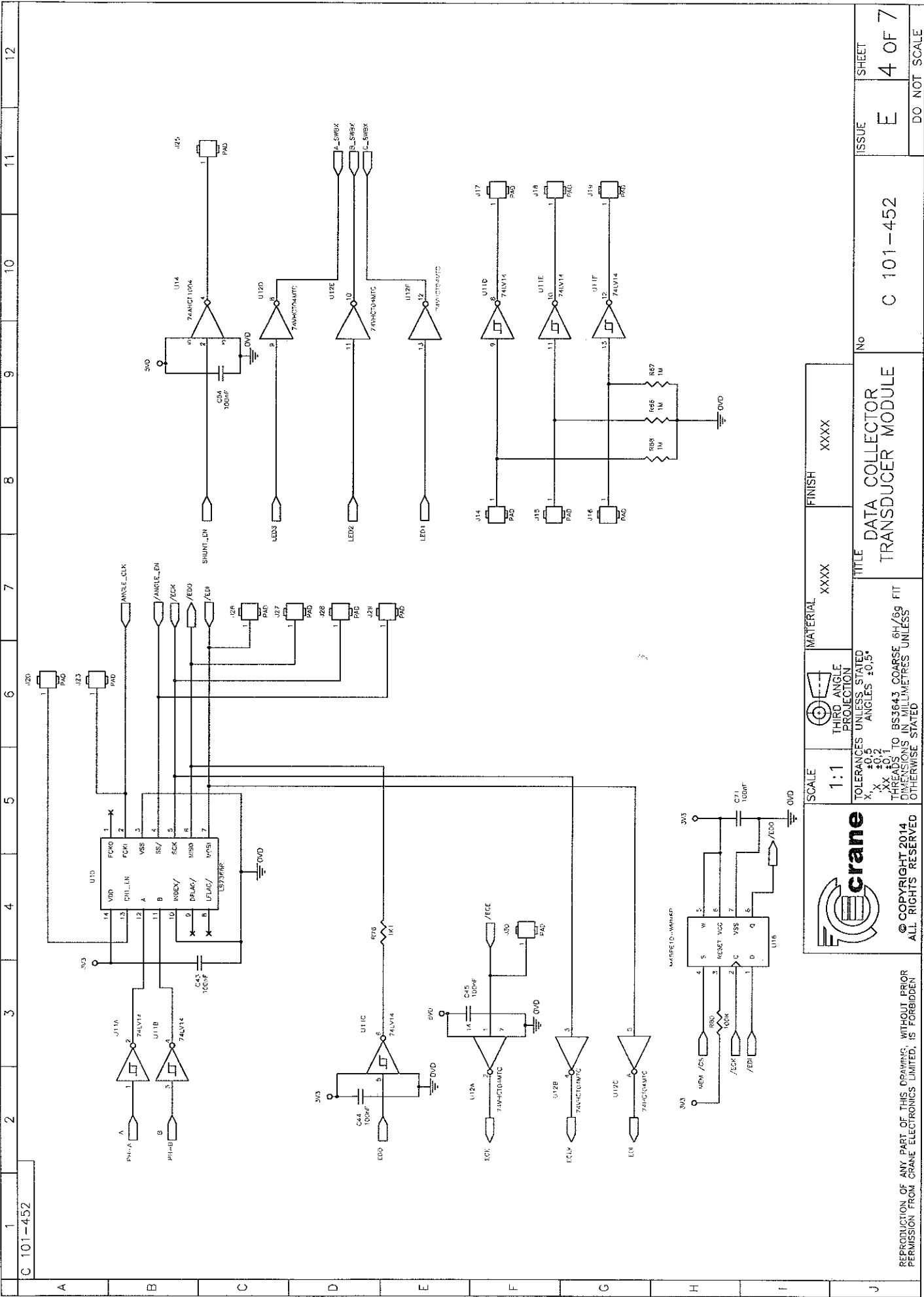
ISSUE

E

SHEET

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SCALE
1:1

THIRD ANGLE
PROJECTION

TOLERANCES UNLESS STATED
X1 40.5
X2 40.2
X3 40.5
X4 40.5
X5 40.5
X6 40.5
X7 40.5
X8 40.5
X9 40.5
X10 40.5
X11 40.5
X12 40.5
X13 40.5
X14 40.5
X15 40.5
X16 40.5
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X94 40.5
X95 40.5
X96 40.5
X97 40.5
X98 40.5
X99 40.5
X100 40.5

MATERIAL XXXX

FINISH XXXX

XXXX

DATA COLLECTOR
TRANSDUCER MODULE

No

C 101-452

ISSUE

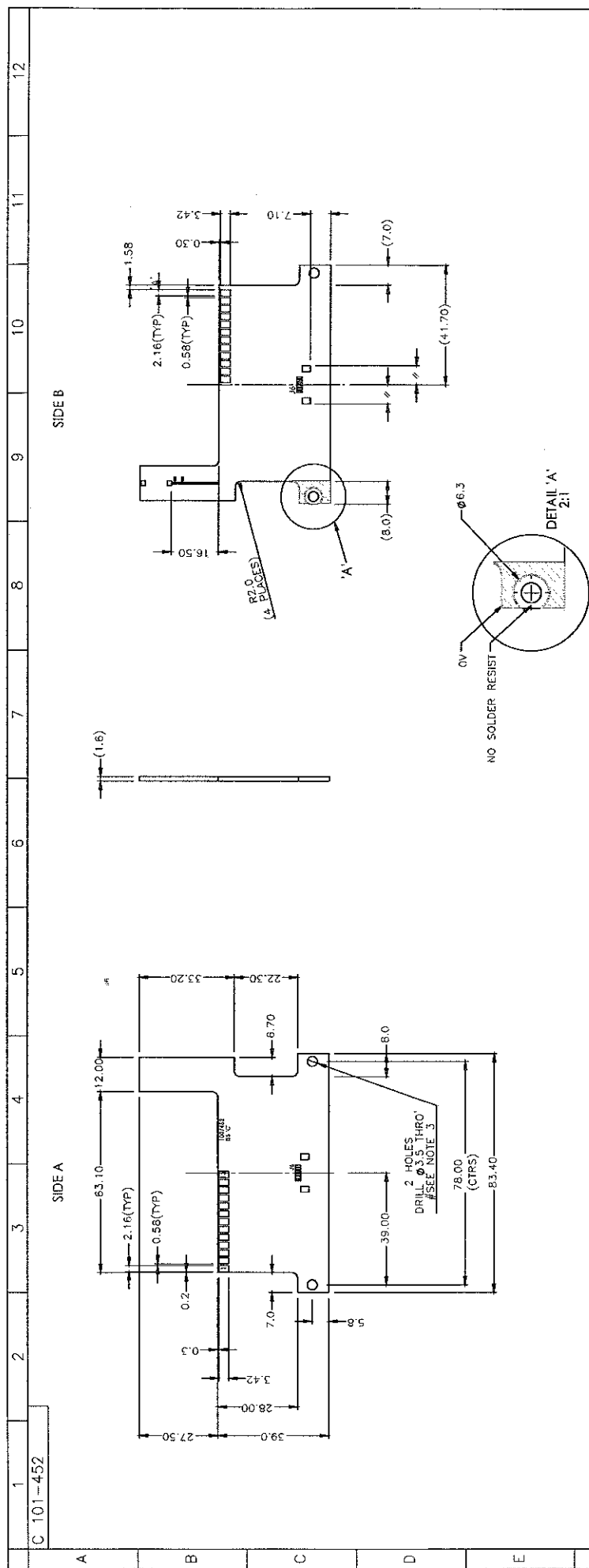
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SHEET

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DO NOT SCALE

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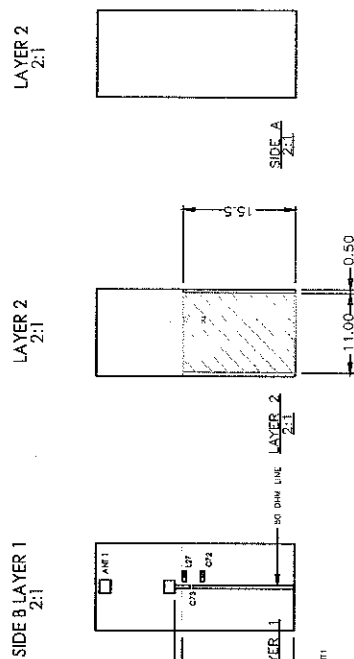
MATERIAL:
GLASS FIBRE LAMINATE 1.6mm ± 10% THICK, DOUBLE SIDED COPPER CLAD
1oz/sq.ft COPPER BOARD TO BE RoHS COMPLIANT

FINISH:
SOLDER RESIST IN GREEN ON BOTH SIDES OF BOARD.

SILK SCREEN IN WHITE
P.C.B. ARTWORK No. 100/452 AND CURRENT ISSUE 'C' TO BE CLEARLY MARKED IN
COPPER

NOTES:

1. ALL CONNECTORS AND TEST POINTS TO BE ON SIDE B
2. REMOVE ALL BURRS AND SHARP EDGES
3. NO THROUGH PLATING FOR 2 Ø3.5 HOLES
4. HATCHED AREA TO BE ØV
5. GROUND LAYER MUST BE DIRECTLY UNDER SIDE B



	SCALE 1:1	 THIRD ANGLE PROJECTION	MATERIAL XXXX	FINISH XXXX	No C 101-452	ISSUE E	SHEET 6 OF 7
	TOLERANCES UNLESS STATED X, X ⁺ ±0.5 XX ±0.1 THREADS TO BS3643 COARSE 6H/6g FIT DIMENSIONS IN MILLIMETRES UNLESS OTHERWISE STATED					TITLE DATA COLLECTOR TRANSDUCER MODULE	
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